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LIU et al.(10) **Pub. No.: US 2022/0368303 A1**(43) **Pub. Date: Nov. 17, 2022**(54) **BLACKENED WAFERS AND METHOD FOR
MANUFACTURING THE SAME, AND WAVE
FILTER DEVICE HAVING THE SAME****Related U.S. Application Data**(63) Continuation-in-part of application No. PCT/
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Quanzhou City (CN)(21) Appl. No.: **17/874,905**(22) Filed: **Jul. 27, 2022**(57) **ABSTRACT**

A method for blackening at least one wafer includes: (a) performing a reduction treatment on the at least one wafer; and (b) illuminating the at least one wafer with an ultraviolet light. The at least one wafer after the illumination of the UV light has a blackening uniformity value (DE value) smaller than 0.6, and a chromatic value (L value) smaller than 54. In addition, a blackened wafer made from the method is also provided.

